

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	14	("20020135057" "20020196650" "5040052" "5422435" "5641113" "6489676" "7145225").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 13:43
L16	1415	228/180.1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 13:46
L17	18	(bump solder ball) with stack and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 13:46
L18	86	("3496428" "3512051" "3761309" "3809625" "3821785" "3986255" "4545610" "4626479" "4664309" "4673772" "4739917" "4783722").PN. OR ("5130779"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 13:47
L19	76	("3597834" "3770874" "3921285" "3922777" "4047290" "4074342" "4447857" "4529835" "4572925" "4617730" "4638400" "4685030").PN. OR ("4783722"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 13:51
L20	68	("5162257").URPN.	USPAT	OR	ON	2008/01/04 13:53
L21	893	((ic integrated near2 circuit micro\$2electronic die semiconductor silicon Microelectronic chip microdevice micro near2 device) near3 package).bstx. and (bump c4 ball solder)near2 stack\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 15:44
L22	421	21	USPAT	OR	ON	2008/01/04 14:02

EAST Search History

L23	52	("20020011666" "5210939" "5261989" "5420461" "5506756" "5519580" "5707247" "5751556" "5757071" "5787575" "5812379" "5880530" "5883783" "5889652" "5889655" "5893725" "5898222" "5966020" "6016852" "6030854" "6031283" "6043559" "6088915" "6118182" "6120885" "6177729" "6206272" "6238948" "6242803" "6271111" "6281581" "6307160" "6312830" "6331446" "6359372" "6365500" "6365973" "6413849" "6429383" "6440770" "6452502" "6461954" "6489557" "6490166" "6498086" "6509530" "6512861" "6521996" "6528345" "6535386" "6548386" "6610591").PN. OR ("7242097").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:05
L24	14	("4833568" "5571754").PN. OR ("6323546").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:17
L25	11	("3148310" "4394712" "5129142" "5266912" "5329423" "5642261" "5896276").PN. OR ("6191370"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:19
L26	27	("3148310").URPN.	USPAT	OR	ON	2008/01/04 14:20
L27	26	("3148310" "3541222" "3835531" "3998824" "4050756" "4136275" "4346516" "4644101" "4761871" "4902857" "4931598" "4966857" "5121299" "5172303").PN. OR ("5401911").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:22
L28	2	"20050121764".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L29	2843	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L30	2229	L29 and (bump solder ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26

EAST Search History

L31	6	("5726493" "5756380" "6489676"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L32	33	("5726493" "6239496" "6303997" "6329915" "6348728").PN. OR ("6489676").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L33	2	"20050121764".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L34	2	"5422430".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L35	2	"5422435".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L36	2248	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L37	0	L36 and flip adj chip]	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L38	817	L36 and flip adj chip.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L39	598	L36 and flip adj chip	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L40	585	L36 and flip adj chip	USPAT	OR	ON	2008/01/04 14:26

EAST Search History

L41	1227	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L42	970	L41 and (bump solder ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L43	559	L41 and (bump solder ball)	USPAT	OR	ON	2008/01/04 14:26
L44	70	("3851221" "4567643" "4730232" "4763188" "4982265" "4996587" "5012323" "5025306" "5040052" "5124783" "5138438" "5140404" "5165067" "5168368" "5198888" "5229647" "5273938" "5291061" "5323060" "5334875" "5347429" "5422435" "5426563" "5432729" "5462624" "5463253" "5473196" "5495394" "5495398" "5498901" "5502289" "5514907" "5569625" "5581498" "5587341" "5614766" "5637536" "5637912" "5682062" "5689135" "5696031" "5715147" "5721452" "5739581" "5783870" "5793108" "5798014" "5815372" "5861666" "5872025" "5885849" "5886412" "5917242" "5952611" "5963794" "5973403" "6005778" "6051886" "6057598" "6072243" "6080264" "6133637" "6161753" "6184463" "6214641" "6232561" "6235554" "6316838" "6340842" "RE36613").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L45	87	("3300686" "3312878" "3372309" "3437882" "4074342" "4225900" "4398208" "4500905" "4698662" "4706166" "4774632" "4825284" "4922378").PN. OR ("5040052"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L46	0	mother adj board with doulbe near data near rate near memory	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L47	3	mother adj board with double near data near rate near memory	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26

EAST Search History

L48	2	"5,422,435".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L49	265	epoxy same phenol\$4 same accelerator same filler same viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L50	239	epoxy same phenol\$4 same accelerator same filler same viscosity	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L51	2	("6284818" "6632881").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L52	2	"20040207073".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L53	2	"6744135".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L54	5	("6020629" "6528882").PN. OR ("6744135").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L55	15	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L56	15	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L57	6	elenius.in. and redistribution	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L58	10	("20020135057" "20020196650" "50 40052" "5422435" "6489676").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26

EAST Search History

L59	2843	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L60	2248	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L61	0	L60 and flip adj chip]	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L62	817	L60 and flip adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L63	1227	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L64	970	L63 and (bump solder ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L65	0	mother adj board with doulbe near data near rate near memory	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L66	2	"20040207073".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L67	15	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26

EAST Search History

L68	15	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L69	2	"20050121764".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L70	6	("5726493" "5756380" "6489676"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L71	33	("5726493" "6239496" "6303997" "6329915" "6348728").PN. OR ("6489676").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L72	2	"20050121764".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L73	2	"5422430".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L74	2	"5422435".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26

EAST Search History

L75	70	("3851221" "4567643" "4730232" "4763188" "4982265" "4996587" "5012323" "5025306" "5040052" "5124783" "5138438" "5140404" "5165067" "5168368" "5198888" "5229647" "5273938" "5291061" "5323060" "5334875" "5347429" "5422435" "5426563" "5432729" "5462624" "5463253" "5473196" "5495394" "5495398" "5498901" "5502289" "5514907" "5569625" "5581498" "5587341" "5614766" "5637536" "5637912" "5682062" "5689135" "5696031" "5715147" "5721452" "5739581" "5783870" "5793108" "5798014" "5815372" "5861666" "5872025" "5885849" "5886412" "5917242" "5952611" "5963794" "5973403" "6005778" "6051886" "6057598" "6072243" "6080264" "6133637" "6161753" "6184463" "6214641" "6232561" "6235554" "6316838" "6340842" "RE36613").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L76	87	("3300686" "3312878" "3372309" "3437882" "4074342" "4225900" "4398208" "4500905" "4698662" "4706166" "4774632" "4825284" "4922378").PN. OR ("5040052"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L77	3	mother adj board with double near data near rate near memory	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L78	2	"5,422,435".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L79	2	("6284818" "6632881").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L80	2	"6744135".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L81	5	("6020629" "6528882").PN. OR ("6744135").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26

EAST Search History

L82	6	elenius.in. and redistribution	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L83	265	epoxy same phenol\$4 same accelerator same filler same viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L84	239	epoxy same phenol\$4 same accelerator same filler same viscosity	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L85	559	L63 and (bump solder ball)	USPAT	OR	ON	2008/01/04 14:26
L86	598	L60 and flip adj chip	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L87	585	L60 and flip adj chip	USPAT	OR	ON	2008/01/04 14:26
L88	2229	L59 and (bump solder ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L89	1321	lithographic adj apparatus.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L90	0	alignent adj mark with anisotropically with etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L91	0	alignent adj mark with anisotropically near2 etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L92	0	alignent adj mark same anisotropically near2 etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26

EAST Search History

L93	18	alignment adj mark same anisotropically near2 etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L94	107	alignment adj mark and (anisotropically and wet) with etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L95	251	alignment adj mark and reactive near4 plasma with etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L96	9	alignment adj mark and reactive near4 plasma with etching same anisotropically	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L97	32	alignment adj mark and wet with etching same anisotropically	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L98	151	and\$1j\$2.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L99	4	("5151771" "5172303" "5739581" "5963430").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L100	104	("3379937" "4288841" "4437718" "4617730" "4654694" "4691225" "4940181" "4969827" "5016138").PN. OR ("5172303").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L101	185	("3214827" "3775844" "4225900" "4941033" "4982265" "5046238" "5138438" "5148265" "5148266" "5172303" "5198888" "5222014" "5247423" "5281852" "5334875" "5347159" "5390844" "5397916" "5398863" "5422435" "5426563" "5440171" "5454160" "5455740" "5479319" "5489749" "5491302" "5543664" "5656856").PN. OR ("5861666").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26

EAST Search History

L102	55	("5006922" "5102829" "5172303" "5200366" "5291062" "5334857" "5433822" "5455456" "5468999" "5608265").PN. OR ("5726493"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L103	9	("5200809" "5726493" "5886408" "6239496" "6303997" "6329915" "6331450" "6348728" "6613606").PN. OR ("6812066"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L104	1	"4857973".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L105	2248	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L106	0	L105 and flip adj chip]	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L107	0	mother adj board with doulbe near data near rate near memory	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L108	0	aligment adj mark with anisotropically near2 etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L109	1227	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L110	970	L109 and (bump solder ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L111	2	"5422430".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26

EAST Search History

L112	2	"20050121764".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L113	15	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L114	2	"20040207073".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L115	15	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L116	251	alignment adj mark and reactive near4 plasma with etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L117	2	"20040207073".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L118	0	mother adj board with doulbe near data near rate near memory	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L119	2248	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L120	2843	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26

EAST Search History

L121	817	L119 and flip adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L122	0	L119 and flip adj chip]	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L123	1227	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:26
L124	970	L123 and (bump solder ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L125	1	"4857973".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L126	55	("5006922" "5102829" "5172303" "5200366" "5291062" "5334857" "5433822" "5455456" "5468999" "5608265").PN. OR ("5726493"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:26
L127	239	epoxy same phenol\$4 same accelerator same filler same viscosity	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L128	265	epoxy same phenol\$4 same accelerator same filler same viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:26
L129	104	("3379937" "4288841" "4437718" "4617730" "4654694" "4691225" "4940181" "4969827" "5016138").PN. OR ("5172303"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L130	2	"5,422,435".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27

EAST Search History

L131	151	and\$1j\$2.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L132	2	("6284818" "6632881").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L133	10	("20020135057" "20020196650" "5040052" "5422435" "6489676").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L134	2	"20050121764".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L135	185	("3214827" "3775844" "4225900" "4941033" "4982265" "5046238" "5138438" "5148265" "5148266" "5172303" "5198888" "5222014" "5247423" "5281852" "5334875" "5347159" "5390844" "5397916" "5398863" "5422435" "5426563" "5440171" "5454160" "5455740" "5479319" "5489749" "5491302" "5543664" "5656856").PN. OR ("5861666").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L136	9	("5200809" "5726493" "5886408" "6239496" "6303997" "6329915" "6331450" "6348728" "6613606").PN. OR ("6812066"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L137	4	("5151771" "5172303" "5739581" "5963430").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L138	817	L105 and flip adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L139	87	("3300686" "3312878" "3372309" "3437882" "4074342" "4225900" "4398208" "4500905" "4698662" "4706166" "4774632" "4825284" "4922378").PN. OR ("5040052"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27

EAST Search History

L140	9	alignment adj mark and reactive near4 plasma with etching same anisotropically	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L141	15	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L142	87	("3300686" "3312878" "3372309" "3437882" "4074342" "4225900" "4398208" "4500905" "4698662" "4706166" "4774632" "4825284" "4922378").PN. OR ("5040052").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L143	0	alignent adj mark with anisotropically with etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L144	2	"5422435".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L145	70	("3851221" "4567643" "4730232" "4763188" "4982265" "4996587" "5012323" "5025306" "5040052" "5124783" "5138438" "5140404" "5165067" "5168368" "5198888" "5229647" "5273938" "5291061" "5323060" "5334875" "5347429" "5422435" "5426563" "5432729" "5462624" "5463253" "5473196" "5495394" "5495398" "5498901" "5502289" "5514907" "5569625" "5581498" "5587341" "5614766" "5637536" "5637912" "5682062" "5689135" "5696031" "5715147" "5721452" "5739581" "5783870" "5793108" "5798014" "5815372" "5861666" "5872025" "5885849" "5886412" "5917242" "5952611" "5963794" "5973403" "6005778" "6051886" "6057598" "6072243" "6080264" "6133637" "6161753" "6184463" "6214641" "6232561" "6235554" "6316838" "6340842" "RE36613").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L146	33	("5726493" "6239496" "6303997" "6329915" "6348728").PN. OR ("6489676").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27

EAST Search History

L147	6	("5726493" "5756380" "6489676"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L148	5	("6020629" "6528882").PN. OR ("6744135").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L149	265	epoxy same phenol\$4 same accelerator same filler same viscosity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L150	3	mother adj board with double near data near rate near memory	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L151	2	"5,422,435".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L152	2	("6284818" "6632881").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L153	2	"6744135".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L154	5	("6020629" "6528882").PN. OR ("6744135").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L155	6	elenius.in. and redistribution	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L156	18	alignment adj mark same anisotropically near2 etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L157	2	"5422435".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27

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L158	2	"20050121764".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L159	6	("5726493" "5756380" "6489676"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L160	33	("5726493" "6239496" "6303997" "6329915" "6348728").PN. OR ("6489676").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L161	2	"5422430".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L162	70	("3851221" "4567643" "4730232" "4763188" "4982265" "4996587" "5012323" "5025306" "5040052" "5124783" "5138438" "5140404" "5165067" "5168368" "5198888" "5229647" "5273938" "5291061" "5323060" "5334875" "5347429" "5422435" "5426563" "5432729" "5462624" "5463253" "5473196" "5495394" "5495398" "5498901" "5502289" "5514907" "5569625" "5581498" "5587341" "5614766" "5637536" "5637912" "5682062" "5689135" "5696031" "5715147" "5721452" "5739581" "5783870" "5793108" "5798014" "5815372" "5861666" "5872025" "5885849" "5886412" "5917242" "5952611" "5963794" "5973403" "6005778" "6051886" "6057598" "6072243" "6080264" "6133637" "6161753" "6184463" "6214641" "6232561" "6235554" "6316838" "6340842" "RE36613").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L163	2	"20050121764".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27

EAST Search History

L164	3	<i>mother adj board with double near data near rate near memory</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L165	239	<i>epoxy same phenol\$4 same accelerator same filler same viscosity</i>	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L166	559	<i>L123 and (bump solder ball)</i>	USPAT	OR	ON	2008/01/04 14:27
L167	559	<i>L109 and (bump solder ball)</i>	USPAT	OR	ON	2008/01/04 14:27
L168	598	<i>L119 and flip adj chip</i>	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L169	585	<i>L119 and flip adj chip</i>	USPAT	OR	ON	2008/01/04 14:27
L170	598	<i>L105 and flip adj chip</i>	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L171	585	<i>L105 and flip adj chip</i>	USPAT	OR	ON	2008/01/04 14:27
L172	1321	<i>lithographic adj apparatus.clm.</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L173	2229	<i>L120 and (bump solder ball)</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L174	2	<i>"5,422,435".pn.</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L175	2	<i>"6744135".pn.</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27

EAST Search History

L176	2	"6489676".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L177	107	alignment adj mark and (anisotropically and wet) with etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L178	32	alignment adj mark and wet with etching same anisotropically	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L179	2843	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/04 14:27
L180	0	alignent adj mark same anisotropically near2 etching	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L181	15	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L182	6	elenius.in. and redistribution	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L183	2229	L179 and (bump solder ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L184	175	stacked near1 ball and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L185	488	stacked near1 ball	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27

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L186	69	stacked near1 ball and IC	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L187	189	stacked near1 ball and chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L188	28	L187 not L184	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L189	0	("2002/0015340").URPN.	USPAT	OR	ON	2008/01/04 14:27
L190	14	L186 not L184	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L191	152	stacked near1 bga	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L192	2	"5594275".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L193	79	("5594275").URPN.	USPAT	OR	ON	2008/01/04 14:27
L194	8	("20040145051" "6339254" "6369448" "6525413").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L195	127	stacked near1 bump and (IC integrated near1 circuit chip die wafer silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27

EAST Search History

L196	32	("5291061" "5302778" "5435734" "5477082" "5477086" "5532519" "5558271" "5719436" "5767580" "5777345" "5790839" "5793101" "5883814" "5900676" "5914535" "5973924" "6150724" "6222246" "6232667" "6310403" "6376915" "RE35119" "RE36613").PN. OR ("6525413").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L197	1	"5767573".PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L198	2	"6455785".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L199	1	(US-6455785-\$.did.	USPAT	OR	ON	2008/01/04 14:27
L200	1	L199 and solder	USPAT	OR	ON	2008/01/04 14:27
L201	15	("5060844" "5147084" "5251806" "5492266" "5493075" "5542601" "5598036" "5641113" "5767580" "5825629" "5889326" "5953623" "6199273" "6225206" "6229220").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/04 14:27
L202	1	(US-6225206-\$.did.	USPAT	OR	ON	2008/01/04 14:27
L203	1	(US-6225206-\$.did. and solder	USPAT	OR	ON	2008/01/04 14:27
L204	16	("5677569" "5818107" "5903437" "6 188578" "6297074" "6303997" "636 2530" "6414391").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L205	2	jp-63128736-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L206	2	"20060208765".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27
L207	2	"5641113".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 14:27

EAST Search History

L208	472	21 not 22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 15:44
L209	1126	stack\$3 and package and (solder bump ball) and (IC semiconductor integrated near2 circuit chip die silicon microelectronic micro\$3electronic)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 16:34
L210	158	stack\$3 near3(solder bump ball) and package and (IC semiconductor integrated near2 circuit chip die silicon microelectronic micro\$3electronic)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 16:35
L211	158	stack\$3 near3 (solder bump ball) and package and (IC semiconductor integrated near2 circuit chip die silicon microelectronic micro\$3electronic)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/04 16:38
L212	69	(stack\$3 near3 (solder bump ball) and package and (IC semiconductor integrated near2 circuit chip die silicon microelectronic micro\$3electronic)).clm.	US-PGPUB	OR	ON	2008/01/04 16:38